



SCN-406

IEC 61850-3, IEEE1613
2U FANLESS SYSTEM



- Intel 10th Gen Xeon® W-1200/ Core i Processor
- 4 x DDR4 up to 128GB
- 2 x RJ45 GbE LAN, 2 x RJ45 10GbE LAN (by option), 1 x IPMI, 4 x USB3.2, 2 x USB2.0, 2 x DP, 1 x VGA, 1 x DVI-D
- 4 x 2.5" Easy swap SSD/HDD Tray (Support RAID 0,1,5,10)
- 3 x PCIe Expansion Slots
- Trusted Platform Module

Specifications

SYSTEM

CPU	10th Generation Intel® Xeon® W-1200 Processors Intel® Xeon® W-1290TE Processor (20M Cache, up to 4.50 GHz) Intel® Xeon® W-1250TE Processor (12M Cache, up to 3.80 GHz) 10th Generation Intel® Core™ i9/i7/i5 Processors Intel® Core™ i9-10900TE(20M Cache, up to 4.60 GHz) Intel® Core™ i7-10700TE(16M Cache, up to 4.50 GHz) Intel® Core™ i5-10500TE(12M Cache, up to 3.70 GHz)
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Memory type	4 x DDR4 up to 128GB
Expansion Slot	1 PCI-E 3.0 x16 2 PCI-E 3.0 x4
Storage Device	4 x 2.5" Easy swap HDD/SSD Tray (Support RAID 0,1,5,10)

REAR I/O

Power Button	1 x w/Indicator LED
USB	2 x USB 2.0

FRONT I/O

Power Input	2 x 100V~240V AC-IN
LAN	2 x RJ45 GbE LAN ; 2 x RJ45 10GbE LAN (by option) ; 1 x IPMI
USB	4 x USB 3.2
DisplayPort	2 x DP
DVI	1 x DVI-D
VGA	1

OPTIONAL

Dual 10GbE SFP+ Module	INTEL X710 Dual 10GbE SFP+ LAN card
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POWER

Power Input	100V~240V AC-IN, 2 x 200W AC/DC Redundant Power Supply
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OS SUPPORT LIST

Windows	Windows 10 x64
Linux	Ubuntu, Red Hat

MECHANICAL AND ENVIRONMENTAL

Dimension	430 x 450 x 88 mm (W x D x H)
Operating Temp.	-20 to 60°C
Storage Temp.	-40°C to 85°C
Relative Humidity	5% to 95%, non-condensing
Standards	CE, FCC, MIL-STD 810G Compliance
System Design	Fanless
Mounting	2U Rackmount
MIL-STD-810G	Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
EMC	CE, FCC compliant
Green Product	RoHS, WEEE compliance

Ordering Information

SCH-406-01

2U 19" Power Automation Fanless Server Computer with Intel 10th Gen [Xeon® W-1200](#) or [Core™ i9/i7/i5](#) Processor, 2 × RJ45 GbE, [2 x 10GbE](#), 100V~240V AC-in, 2 x 200W AC/DC Redundant Power Supply, Operating Temperature -20~+60°C

SCH-406-02

2U 19" Power Automation Fanless Server Computer with Intel 10th Gen [Xeon® W-1200](#) Processor, 2 × RJ45 GbE, 100V~240V AC-in, 2 x 200W AC/DC Redundant Power Supply, Operating Temperature -20~+60°C

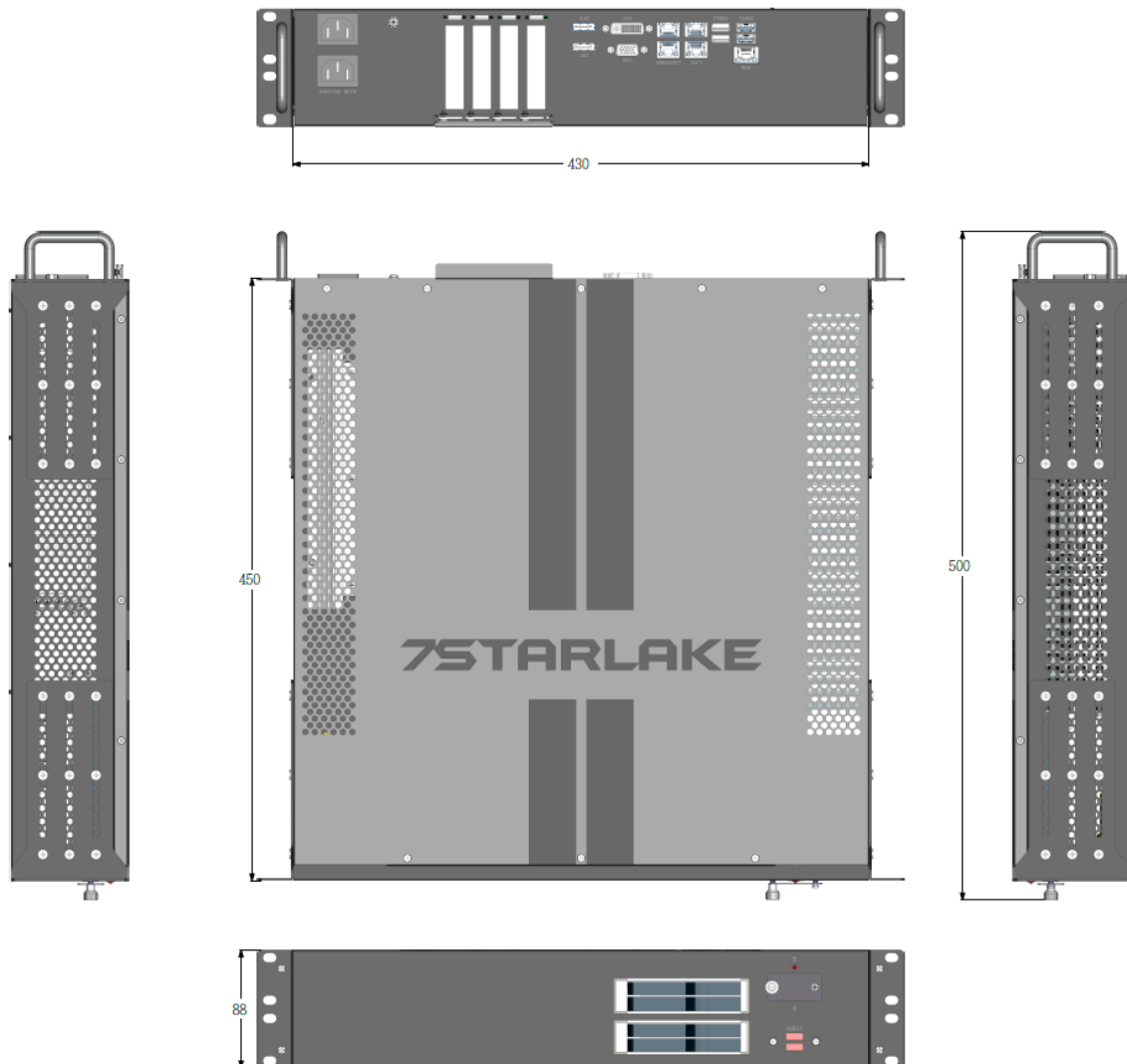
SCH-406-03

2U 19" Power Automation Fanless Server Computer with Intel 10th Gen [Core™ i9/i7/i5 Processor](#), 2 × RJ45 GbE, 100V~240V AC-in, 2 x 200W AC/DC Redundant Power Supply, Operating Temperature -20~+60°C

Optional Accessories

INTEL X710 Dual 10GbE SFP+ LAN card

Dimension



Front Panel I/O Placement



Rear Panel I/O Placement

